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Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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 $V_{\rm DS}$

R_{DS(on)}

 $I_{D(lim)}$

I_{D(ISO)}

Product Summary

Drain source voltage

On-state resistance

Nominal load current

Clamping energy

Current limit



Features

- Logic Level Input
- Input Protection (ESD)
- Thermal shutdown with latch

RoHS

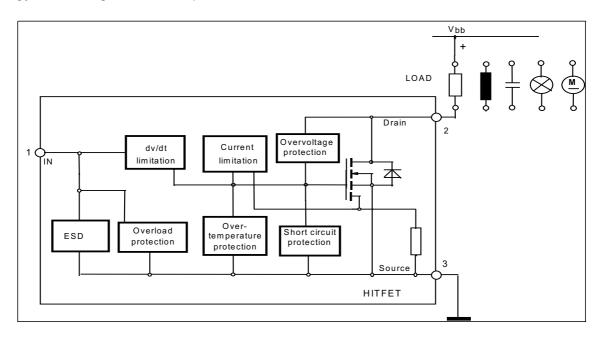
- Green product (RoHS compliant)
- Short circuit and Overload protection
- Overvoltage protection
- Current limitation
- Status feedback with external input resistor
- Analog driving possible
- AEC qualified
- Green product (RoHS compliant)

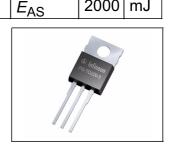
Application

- All kinds of resistive, inductive and capacitive loads in switching or linear applications
- µC compatible power switch for 12 V and 24 V DC applications
- Replaces electromechanical relays and discrete circuits

General Description

N channel vertical power FET in Smart SIPMOS[®] chip on chip technology. Providing embedded protection functions.





V

А

A

mΩ

60

50

21

7

2000 mJ



Parameter	Symbol	Value	Unit
Drain source voltage	V _{DS}	60	V
Drain source voltage for short circuit protection	V _{DS(SC)}	32	
Continuous input current ¹⁾	I _{IN}		mA
$-0.2V \le V_{\rm IN} \le 10V$		no limit	
$V_{\rm IN}$ < -0.2V or $V_{\rm IN}$ > 10V		<i>I</i> _{IN} ≤ 2	
Operating temperature	T _j	- 40 +150	°C
Storage temperature	T _{stg}	- 55 +150	
Power dissipation	P _{tot}	90	W
<i>T</i> _C = 25 °C			
Unclamped single pulse inductive energy	E _{AS}	2000	mJ
$I_{D(ISO)} = 7 A$			
Electrostatic discharge voltage (Human Body Model)	V _{ESD}	3000	V
according to MIL STD 883D, method 3015.7 and			
EOS/ESD assn. standard S5.1 - 1993			
Load dump protection $V_{\text{LoadDump}}^{(2)} = V_{\text{A}} + V_{\text{S}}$	V _{LD}		
V _{IN} =low or high; V _A =13.5 V			
t _d = 400 ms, <i>R</i> I = 2 Ω, <i>I</i> D=0,5*7A		90	
t_{d} = 400 ms, R_{I} = 2 Ω , I_{D} = 7A		74	

Maximum Ratings at Tj = 25 °C unless otherwise specified

Thermal resistance

junction - case:	R _{thJC}	1.4	K/W
junction - ambient:	R _{thJA}	75	
SMD version, device on PCB: ³⁾	R _{thJA}	45	

¹In case of thermal shutdown a minimum sensor holding current of 500 μ A has to be guaranteed (see also page 3).

 $^2V_{\text{Loaddump}}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839

³ Device on 50mm*50mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70µm thick) copper area for Drain connection. PCB mounted vertical without blown air.



Electrical Characteristics

Parameter	Symbol	Values			Unit	
at T _j =25°C, unless otherwise specified		min.	typ.	max.	1	
Characteristics	•	·	·			
Drain source clamp voltage	V _{DS(AZ)}	60	-	73	V	
<i>T</i> _j = - 40+ 150°C, <i>I</i> _D = 10 mA						
Off state drain current	I _{DSS}	-	-	10	μA	
V_{DS} = 32 V, T_{j} = -40+150 °C, V_{IN} = 0 V						
Input threshold voltage	V _{IN(th)}	1.3	1.7	2.2	V	
<i>I</i> _D = 1,4 mA						
Input current - normal operation, <i>I</i> _D < <i>I</i> _{D(lim)} :	/IN(1)	-	30	55	μA	
$V_{\rm IN} = 10 \text{ V}$						
Input current - current limitation mode, $I_{\rm D}=I_{\rm D(lim)}$:	I _{IN(2)}	60	150	350		
$V_{\rm IN} = 10 \ {\rm V}$						
Input current - after thermal shutdown, <i>I</i> _D =0 A:	I _{IN(3)}	1000	2500	4000		
$V_{\rm IN} = 10 \text{ V}$						
Input holding current after thermal shutdown ¹⁾	I _{IN(H)}					
<i>T</i> _j = 25 °C		500	-	-		
$T_{\rm j}$ = 150 °C		300	-	-		
On-state resistance	R _{DS(on)}				mΩ	
$V_{\rm IN}$ = 5 V, $I_{\rm D}$ = 7 A, $T_{\rm j}$ = 25 °C		-	50	60		
$V_{\rm IN}$ = 5 V, $I_{\rm D}$ = 7 A, $T_{\rm j}$ = 150 °C		-	90	120		
On-state resistance	R _{DS(on)}]	
V _{IN} = 10 V, <i>I</i> _D = 7 A, <i>T</i> _j = 25 °C		-	40	50		
$V_{\rm IN}$ = 10 V, $I_{\rm D}$ = 7 A, $T_{\rm j}$ = 150 °C		-	75	100		
Nominal load current (ISO 10483)	I _{D(ISO)}	7	-	-	А	
$V_{\rm IN}$ = 10 V, $V_{\rm DS}$ = 0.5 V, $T_{\rm C}$ = 85 °C						



Electrical Characteristics

Parameter	Symbol	Values			Unit
at T _j =25°C, unless otherwise specified		min.	typ.	max.	
Characteristics					
Initial peak short circuit current limit	I _{D(SCp)}	-	65	-	A
V _{IN} = 10 V, V _{DS} = 12 V					
Current limit ¹⁾	I _{D(lim)}	21	28	40]
$V_{\rm IN}$ = 10 V, $V_{\rm DS}$ = 12 V, $t_{\rm m}$ = 350 µs,					
<i>T</i> _j = -40+150 °C					
Dynamic Characteristics		•			•
Turn-on time $V_{\rm IN}$ to 90% $I_{\rm D}$:	t _{on}		40	100	μs
$R_{\rm L}$ = 2,2 Ω, $V_{\rm IN}$ = 0 to 10 V, $V_{\rm bb}$ = 12 V					
Turn-off time $V_{\rm IN}$ to 10% $I_{\rm D}$:	<i>t</i> off		70	170	
$R_{\rm L}$ = 2,2 Ω, $V_{\rm IN}$ = 10 to 0 V, $V_{\rm bb}$ = 12 V					
Slew rate on 70 to 50% V _{bb} :	-dV _{DS} /dt _{on}		1	3	V/µs
$R_{\rm L}$ = 2,2 Ω , $V_{\rm IN}$ = 0 to 10 V, $V_{\rm bb}$ = 12 V					
Slew rate off 50 to 70% V _{bb} :	dV _{DS} /dt _{off}		1	3	
$R_{\rm I}$ = 2,2 Ω , $V_{\rm IN}$ = 10 to 0 V, $V_{\rm bb}$ = 12 V					

Protection Functions²⁾

Thermal overload trip temperature	T _{it}	150	165	-	°C
Unclamped single pulse inductive energy	E _{AS}				mJ
$I_{\rm D}$ = 7 A, $T_{\rm j}$ = 25 °C, $V_{\rm bb}$ = 32 V		2000	-	-	
$I_{\rm D}$ = 7 A, $T_{\rm j}$ = 150 °C, $V_{\rm bb}$ = 32 V		450	-	-	

Inverse Diode

Inverse diode forward voltage	V _{SD}	-	1.08	-	V
$I_{\rm F}$ = 5*7A, $t_{\rm m}$ = 300 µS, $V_{\rm IN}$ = 0 V					

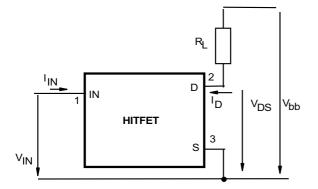
¹Device switched on into existing short circuit (see diagram Determination of I $_{D(lim)}$). If the device is in on condition and a short circuit occurs, these values might be exceeded for max. 50 µs.

²Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

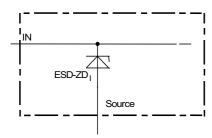


Block Diagramm

Terms

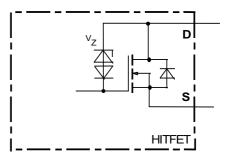


Input circuit (ESD protection)

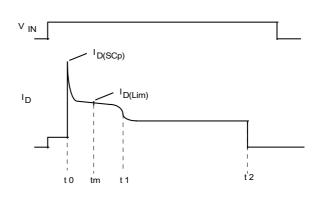


ESD zener diodes are not designed for DC current > 2 mA @ V_{IN} >10V.

Inductive and overvoltage output clamp



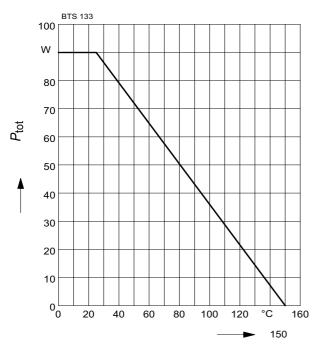
Short circuit behaviour



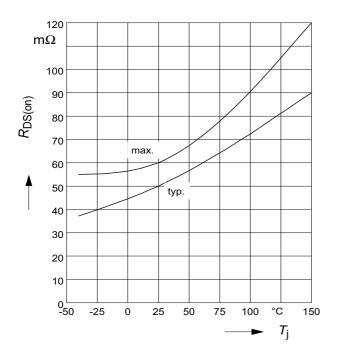
- t₀: Turn on into a short circuit
- tm: Measurementpoint for ID(lim)
- t₁: Activation of the fast temperature sensor and regulation of the drain current to a level where the junction temperature remains constant.
- t₂: Thermal shutdown caused by the second temperature sensor, achieved by an integrating measurement.



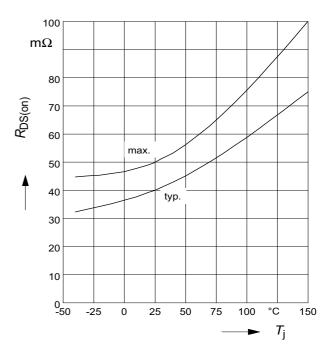
Maximum allowable power dissipation P_{tot} = f(T_c)



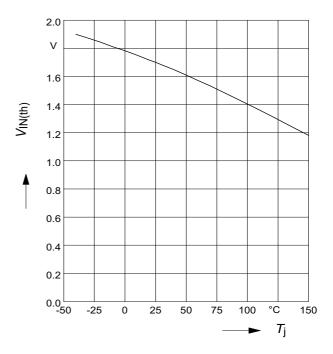
On-state resistance R_{ON} = f(T_j); I_D= 7A; V_{IN}=5V



On-state resistance R_{ON} = f(T_j); I_D=7A; V_{IN}=10V



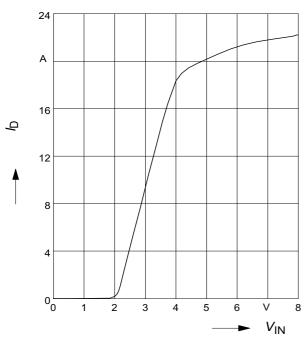
Typ. input threshold voltage V_{IN(th)} = f(T_j); I_D=1,4mA; V_{DS}=12V





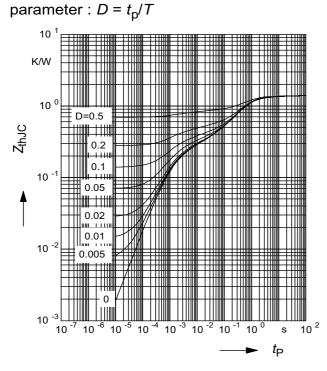


Typ. transfer characteristics I_D = f(V_{IN}); V_{DS}=12V; T_j=25°C

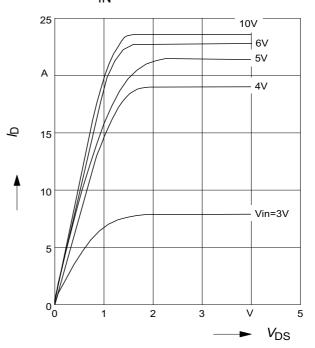


Transient thermal impedance

 $Z_{\text{thJC}} = f(t_{\text{p}})$



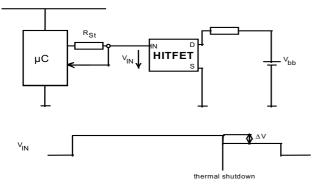
Typ. output characteristic $I_D = f(V_{DS}); T_j=25^{\circ}C$ Parameter: V_{IN}





Application examples:

Status signal of thermal shutdown by monitoring input current



 $\Delta \mathsf{V} = R_{\mathsf{ST}} \, {}^* I_{\mathsf{IN}(3)}$



Package Outlines

1 Package Outlines

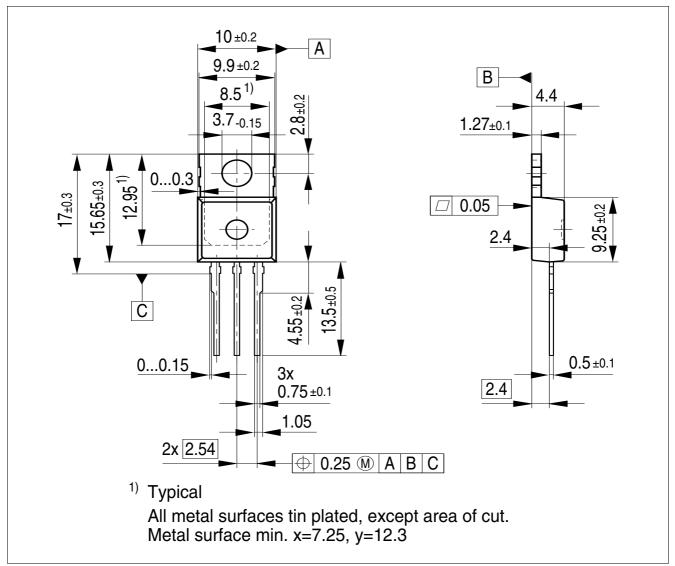


Figure 1 PG-TO220-3-1

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

You can find all of our packages, sorts of packing and others in our Infineon Internet Page "Products": http://www.infineon.com/products.



Revision History

2 Revision History

Version	Date	Changes
Rev. 1.4	2012-07-11	released through hole automotive green Datasheet
		Package drawing update, removed staggered package
		added through hole version in green package
Rev. 1.3	2008-12-10	Package drawing update
Rev. 1.2	2008-08-11	Package information updated, removed through hole version
Rev. 1.1	2008-02-22	Package parameter (humidity and climatic) removed in Maximum ratings AEC icon and RoHS icon added
		Green product and AEC qualified added to feature list
		added Protection footnote on Page 4 and changed front page general description
		Package infromation updated to green
		Green explanation added
Rev. 1.0	2000-05-19	released production version

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